TOSHIBA

RD Number: RD146

RD Title: TB6612FNG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC1	1	10µF 16V	–	–	Electrolytic capacitor		
2	C_VCC2	1	0.1µF 100V	–	–	Chip capacitor	3.2mm×1.6mm	
3	C_VM1	1	10µF 50V	–	–	Electrolytic capacitor		
4	C_VM2	1	0.1µF 100V	–	–	Ceramic capacitor	3.2mm×1.6mm	
5	C_AO1	0	Not mount	–	–	Chip capacitor	3.2mm×1.6mm	✓
6	C_BO1	0	Not mount	–	–	Chip capacitor	3.2mm×1.6mm	✓
7	R_AO1	0	Not mount	–	–	Chip resistor	3.2mm×1.6mm	✓
8	R_BO1	0	Not mount	–	–	Chip resistor	3.2mm×1.6mm	✓
9	CON1	1	Connector 2P	–	–	Connector 2P-2.5		
10	CON2	1	Connector 2P	–	–	Connector 2P-2.5		
11	VM	1	Check terminal	–	–	Check pin		
12	Vcc	1	Check terminal	–	–	Check pin		
13	PWMA	1	Check terminal	–	–	Check pin		
14	AIN2	1	Check terminal	–	–	Check pin		
15	AIN1	1	Check terminal	–	–	Check pin		
16	STBY	1	Check terminal	–	–	Check pin		
17	BIN1	1	Check terminal	–	–	Check pin		
18	BIN2	1	Check terminal	–	–	Check pin		
19	PWMB	1	Check terminal	–	–	Check pin		
20	AO1	1	Check terminal	–	–	Check pin		
21	AO2	1	Check terminal	–	–	Check pin		
22	BO1	1	Check terminal	–	–	Check pin		
23	BO2	1	Check terminal	–	–	Check pin		
24	GND	1	Check terminal	–	–	Check pin		
25	GND2	1	Check terminal	–	–	Check pin		
26	GND3	1	Check terminal	–	–	Check pin		

27	GND4	1	Check terminal	–	–	Check pin		
28	GND5	1	Check terminal	–	–	Check pin		
29	GND6	1	Check terminal	–	–	Check pin		
30	SW_PWMA	1	Pin header	–	–	Jumper		
31		1	Jumper socket	–	–	Short pin		
32	SW_AIN2	1	Pin header	–	–	Jumper		
33		1	Jumper socket	–	–	Short pin		
34	SW_AIN1	1	Pin header	–	–	Jumper		
35		1	Jumper socket	–	–	Short pin		
36	SW_STBY	1	Pin header	–	–	Jumper		
37		1	Jumper socket	–	–	Short pin		
38	SW_BIN1	1	Pin header	–	–	Jumper		
39		1	Jumper socket	–	–	Short pin		
40	SW_BIN2	1	Pin header	–	–	Jumper		
41		1	Jumper socket	–	–	Short pin		
42	SW_PWMB	1	Pin header	–	–	Jumper		
43		1	Jumper socket	–	–	Short pin		
44	JP_VCC	1	Pin header	–	–	Jumper		
45		1	Jumper socket	–	–	Short pin		
46	IC	1	TB6612FNG	TB6612FNG	TOSHIBA	Motor driver IC	SSOP24	

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